

Atty. Docket No. PIA31221/DBE/US  
Serial No: 10/751,200

**Amendments to the Claims**

Please amend the claims as follows:

1. (Currently amended) A method for packaging a multi-chip module, comprising the steps of:
  - (a) connecting connection terminals of a tape of an anisotropic conductive adhesive film, on which a circuit is patterned to bond pads of a chip by applying a first anisotropic conductive adhesive on the tape and using a first C4 process;
  - (b) applying an adhesive on an upper surface of the chip, folding the tape and attaching the folded tape to the upper surface of the chip;
  - (c) forming a plurality of ball terminals on a lower surface of the tape, the ball terminals being electrically connected to the connection terminals of the tape;
  - (d) manufacturing a plurality of individual chip scale packages by repeating the steps (a) to (c); and
  - (e) laminating the individual chip scale packages, wherein the ball terminals of an upper individual chip scale package are electrically connected to the circuit on an outer surface of the tape which covers a lower individual chip scale package.
2. (Previously presented) The method of claim 1, further comprising the step of mounting the ball terminals of a lowest of the individual chip scale packages on a patterned circuit.
- 3-4. (Cancelled)
5. (Previously presented) The method of claim 1, wherein, in the step (b), the adhesive comprises a second anisotropic conductive adhesive.

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6. (Previously presented) The method of claim 1, further comprising the step of providing an uppermost chip scale package on top of the laminated chip scale packages of step (e), wherein the tape covers only a lower surface of the uppermost individual chip scale package.

7. (Previously presented) The method of claim 6, wherein the step of providing an uppermost chip scale package comprises connecting connection terminals of a further tape of a further anisotropic conductive adhesive film on which a further circuit is patterned to bond pads of a further chip by applying a second adhesive on the tape, and forming a further plurality of ball terminals on a lower surface of the further tape, the further plurality of ball terminals being electrically connected to the connection terminals of the further tape.

8. (Previously presented) The method of claim 7, wherein the second adhesive comprises a third anisotropic conductive adhesive.

9. (Previously presented) The method of claim 7, wherein the step of connecting the connection terminals of the further tape uses a second C4 process.

10. (Previously presented) The method of claim 1, comprising the step of patterning the circuit on the tape.

11. (Previously presented) The method of claim 1, wherein, in the step (b), the adhesive comprises a thermal conductive adhesive.

12. (Previously presented) The method of claim 2, wherein the patterned circuit comprises a printed circuit board.